

Product Change Description

SOFTWARE MODIFICATIONS:

Protocol Stack changes: NO
MMS/STK changes: NO
JAVA changes: NO
Other changes detailed: NO

HARDWARE MODIFICATION:

Band changes: NO
Power Amplifier changes: NO
Antenna changes: NO
PCB Layout changes: change supplier
Components on PCB changes: NO
LCD changes: change supplier and model
Speaker changes: NO
Camera changes: NO
Vibrator changes: NO
Bluetooth changes: NO
FM changes: NO
Memory changes: change model and supplier
Other changes: Fingerprint module

MECHANICAL MODIFICATIONS:

Use new metal front/back cover or keypad: NO
Mechanical shell changes: NO.
Other changes detailed: NO

ACCESSORY MODIFICATIONS:

Battery changes: Yes, only increased a new supplier.
AC Adaptor changes: NO
USB Cable changed: NO
Earphone changes: NO

Client:

Name: Hisense International Co., Ltd.

Address: Floor 22, Hisense Tower, 17 Donghai Xi Road, Qingdao, 266071, China

manufacturer:

Name: Hisense Communications Co., Ltd.

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APPROVED BY:

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Date:2017/9/28